

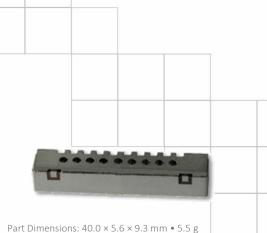


Features

- Low Loss with High Rejection
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade TDD Pico-cells.



Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter with superior rejection, insertion loss, reliability, peak and average power handling compared to other bandpass filter technologies. Also very low group-delay and group-delay variation.

Electrical Specifications

Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -55°C to +85°C
-	50 ohms	-	-
-	-	-	8-10 Watt max
-	-	-	80-100 Watt max
4248-4352	2.0 dB	2.1 dB max	2.3 dB max
4248-4352	0.7 dB	0.8 dB max	0.9 dB max
4248-4352	15 dB	14 dB min	14 dB min
4248-4352	12 ns	15 ns max	15 ns max
4248-4352	4.0 ns	5.0 ns max	5.0 ns max
1-4100	52 dB	47 dB min	47 dB min
4101-4200	30 dB	29 dB min	27 dB min
4400-4499	30 dB	29 dB min	27 dB min
4500-4519	46 dB	45 dB min	45 dB min
4520-6000	50 dB	47 dB min	47 dB min
	(MHz)	(MHz) at 25°C - 50 ohms 4248-4352 2.0 dB 4248-4352 0.7 dB 4248-4352 15 dB 4248-4352 12 ns 4248-4352 4.0 ns 1-4100 52 dB 4101-4200 30 dB 4400-4499 30 dB 4500-4519 46 dB	(MHz) at 25°C at 25°C - 50 ohms

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances. Specification Allowance Insertion Loss 0.1 dB Return Loss 1.0 dB Attenuation 1.0 dB

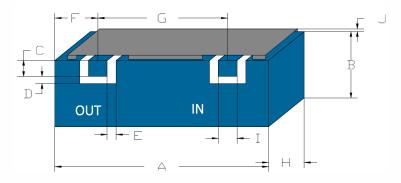
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Preliminary - MMB430A

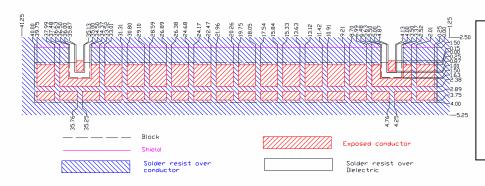
4248-4352MHz MMB Series BPF

Mechanical Drawing



PCB Layout

Dim.	Nominal (mm)	Tolerance (±mm or Max)
Α	40.0	max
В	4.0	max
С	1.0	0.13
D	0.5	0.13
Е	0.5	0.13
F	4.5	0.25
G	31.0	0.13
Н	9.3	max
I	1.0	0.13
J	1.4	0.2

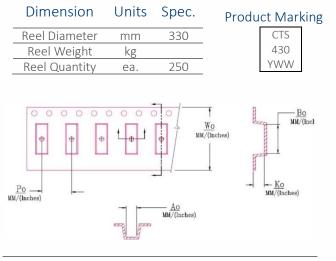


IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

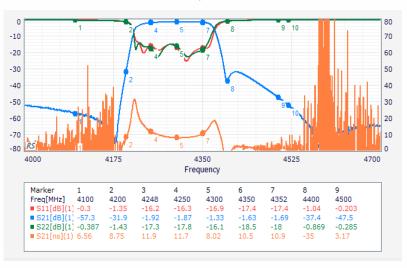
Recommended solder: 6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Packaging and Marking



Wo Ao Bo Ko Po 2.205 in 56.0 mm 0.240 in 6.1 mm 1.587 in 40.3 mm 0.378 in 9.6 mm 0.630 in 16.0 mm

Electrical Response



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